

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0906NS	**Issued**	17. April 2021
MA#	MA005421892		
Package	PG-TDSON-8-51	**Weight***	101.31 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.224	0.22	0.22	2216	2216
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		135	
	non noble metal	zinc	7440-66-6	0.055	0.05		538	
	non noble metal	iron	7439-89-6	1.090	1.08		10762	
	non noble metal	copper	7440-50-8	44.271	43.71	44.85	436993	448428
wire	noble metal	gold	7440-57-5	0.032	0.03	0.03	320	320
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		878	
	plastics	epoxy resin	-	4.090	4.04		40376	
	inorganic material	silicondioxide	60676-86-0	40.282	39.76	43.89	397618	438872
leadfinish	non noble metal	tin	7440-31-5	1.264	1.25	1.25	12474	12474
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.009	0.01		93	
	non noble metal	tin	7440-31-5	0.019	0.02		185	
	non noble metal	lead	7439-92-1	0.348	0.34	0.37	3431	3709
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2249	
	non noble metal	copper	7440-50-8	9.250	9.13	9.36	91306	93695
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com